Product / Package Information

Package	SOIC_N_EP
Body Size (mm)	
Lead Count	16
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes with exemption
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	7.56E-02	86.91	869100	45.41	454099
Thermosets	Epoxy & Phenol Resin	Proprietary	1.11E-02	12.78	127800	6.68	66775
Other inorganic materials	Carbon black	1333-86-4	2.70E-04	0.31	3100	0.16	1620
Subtotal			8.69E-02	100.00	1000000	52.25	522493

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	5.85 E-02	97.50	975000	35.18	351808
Copper & its alloys	Iron	7439-89-6	1.41 E-03	2.35	23500	0.85	8479
Copper & its alloys	Zinc	7440-66-6	7.20 E-05	0.12	1200	0.04	433
Copper & its alloys	Phosphorus	7723-14-0	1.80 E-05	0.03	300	0.01	108
Subtotal			6.00 E-02	100.00	1000000	36.08	360829

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.20 E-04	100.0	1000000	0.19	1923

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	3.65 E-03	100.0	1000000	2.19	21936

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	4.26 E-04	99.0	990000	0.26	2558
Precious metals	Palladium	7440-05-3	4.30 E-06	1.00	10000	0.003	26
Subtotal			4.30 E-04	100.0	1000000	0.26	2584

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	7.51 E-03	100.0	1000000	4.51	45134

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Resin	Proprietary	3.31 E-03	50.00	500000	1.99	19892
Other organic materials	Ethene, tetrafluoro-,homopolymer	9002-84-0	2.98 E-03	45.00	450000	1.79	17903
Other organic materials	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8	3.31 E-04	5.00	50000	0.20	1989
Subtotal			6.62 E-03	100.0	1000000	3.98	39785

Seal Glass

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Ceramics/Glass	Lead borosilicate glass	65997-17-3	7.74 E-04	87.5	875000	0.47	4651
Ceramics/Glass	Aluminosilicate glass	65997-17-3	1.11 E-04	12.5	125000	0.07	664
			8.85 E-04			0.53	5316

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.66 E-01**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary